




Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-04-14
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8HZG*CWB160R	A	BO2A	2015-04-14
Amount	UoM	Unit type	ST ECOPACK Grade	
98.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.50X2.16X3.68	1	J bend	
Comment	SMB CLIP (SOD 6); MD valid for CP: SMP100LC-160.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HZG*CW8160R					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	2.258	mg	supplier	die	Silicon (Si)	7440-21-3		2.192	mg	970771	22367
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.025	mg	11072	255
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.011	mg	4872	112
die (s)				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	3543	82
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1771	41
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	7972	184
Leadframe	Copper & its alloys	36.097	mg	supplier	alloy	Copper (Cu)	7440-50-8		35.293	mg	977727	360133
Leadframe				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.035	mg	970	357
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.769	mg	21304	7847
Soft solder	Solder	2.095	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.959	mg	935084	19990
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.031	mg	14797	316
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.105	mg	50119	1071
Bonding wire	Other inorganic materials	18.33	mg	supplier	wire	Copper (Cu)	7440-50-8		18.33	mg	1000000	187041
encapsulation	Other Organic Materials	38.409	mg	supplier	mold compound	Silica, vitreous	60676-86-0		29.191	mg	760004	297867
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		2.305	mg	60012	23520
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.307	mg	7993	3133
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		3.917	mg	101981	39969
encapsulation				supplier	mold compound	Metal hydroxide	proprietary		0.768	mg	19995	7837
encapsulation				supplier	mold compound	Others	proprietary		1.921	mg	50014	19602
connections coating	Solder	0.811	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.811	mg	1000000	8276